

1. Features

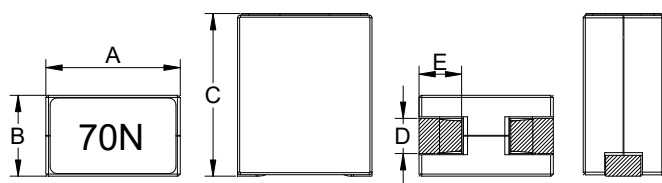
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free & Halogen-Free and RoHS compliant.



2. Applications

Commercial applications.

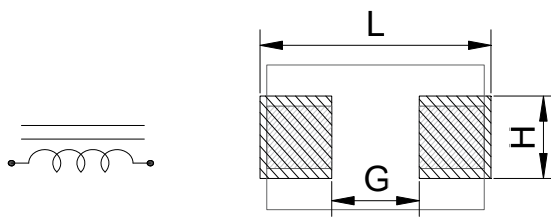
3. Dimensions



A	B	C	D	E
9.7±0.30	5.8±0.20	11.8±0.20	2.40±0.3	3.00±0.3

Unit:mm

Recommend PC Board Pattern



L	G	H
10.3	3.9	3.3

Note: 1.PCB layout is referred to standard IPC-7351B
 2. The above PCB layout reference only.
 3. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering

SEPI	106012	LN	-	70N	L	R1210
A	B	C		D	E	F

A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

F: Code

BxC

Standard

70N=0.07uH

L=±15%, M=±20%

DC Resistance, Marking direction cannot decide polarity.

5. Specification

Part Number	Inductance L0A DC (uh)	I rms (A)	I sat (A) Typ			DCR (mΩ)	Mark
		Typ	25℃	100℃	125℃		
SEPI106012LN-70NM-R1210	0.07±20%	77	135	110	100	0.125±10%	70N
SEPI106012LN-80NL-R1210	0.08±15%	77	135	110	100	0.125±10%	80N
SEPI106012LN-90NL-R1210	0.09±15%	77	130	108	97	0.125±10%	90N
SEPI106012LN-R10L-R1210	0.10±15%	77	125	105	95	0.125±10%	R10
SEPI106012LN-R12L-R1210	0.12±15%	77	105	88	81	0.125±10%	R12
SEPI106012LN-R15L-R1210	0.15±15%	77	83	78	71	0.125±10%	R15
SEPI106012LN-R22L-R1210	0.22±15%	77	60	/	/	0.125±10%	R22
SEPI106012LN-R30L-R1210	0.30±15%	77	46	40	35	0.125±10%	R30
SEPI106012LN-R33L-R1210	0.33±15%	77	40	32	28	0.125±10%	R33
SEPI106012LN-R47L-R1210	0.47±15%	77	25	21	17	0.125±10%	R47

Note:

1. Test frequency : Ls : 100KHz /0.1V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δ T of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃ under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.